



## **For Immediate Release**

### **Teseda Introduces Three Advanced Failure Analysis Tools to Dramatically Reduce Root Cause Resolution and Improve RMA Cycle Time**

PORTLAND, OR. – November 14, 2011 – Teseda Corporation, a leading provider of comprehensive diagnostic solutions for failure analysis and silicon debug, today announced three advanced failure analysis tools aimed at reducing root cause resolution, improving RMA cycle time and empowering failure analysis teams with new fault diagnosis methodologies. The Broken Chain Analyzer, Diagnostic Manager NetXY™ and DC Field Triage™ Package are fully compatible with Teseda's V550™ and V520™ line of benchtop silicon debug and failure analysis test systems and the Teseda Workbench™ software silicon debug environment.

#### **Broken Chain Analyzer**

Teseda's Broken Chain Analyzer software package focuses on accelerating the diagnosis of defective scan chains, a growing issue in failure analysis of newer SoC designs that rely on larger numbers of lengthier scan chains for full testability and fault coverage. At line widths of 65nm and below, scan chain related issues amount to greater than 30% of overall scan failures. Broken Chain Analyzer fully exploits the power of your existing DFT-based tests to automatically analyze captured tester fail logs and detect all common causes of scan chain failures - both hard (stuck-at fails) and soft (timing or voltage-related fails) down to the failing bit location.

#### **Diagnostic Manager NetXY™**

Diagnostic Manager NetXY is a powerful diagnosis tool that maps detected device fails from logical to physical location in a design, dramatically shortening determination of root cause. The newest release of the tool includes logic cone and physical scan chain tracing - powerful new diagnosis features to address EDA-vendor independent failure diagnosis. The new features allow a failure analysis engineer to isolate likely causes of common scan-detected failures such as broken scan chains, logic design problems and via connectivity marginalities faster and with greater precision.

#### **DC Field Triage™ Package**

Teseda's DC Field Triage Package provides the user with easy to use, automated screening tools for DC related device failures. Designed for use by field personnel, the DC Field Triage Package puts device failure triage into the design and field support centers, enabling fast, timely and detailed responses to your customer's quality concerns. Since first-level field screening is done in the field, factory failure analysis tasks are offloaded by as much as 40%.

“We are extremely excited to be announcing our newest state-of-the-art failure analysis solutions”, stated Armagan Akar, President and CEO of Teseda Corporation. “By adopting these new diagnostic tools our customers can leverage the combination of our debug test platforms, and enhanced software diagnosis capabilities to get to the root cause in as little as two days, dramatically improving their quality and saving time and money.”

The new tools are available for immediate delivery. Contact your local Teseda representative for more information.

Teseda will be demonstrating the new failure analysis tools at the 37<sup>th</sup> International Symposium for Testing and Failure Analysis (ISTFA 2011), November 15 - 16, 2011, at the McEnery Convention Center in San Jose, California.

#### **About Teseda**

Teseda’s products leverage Design For Test (DFT) techniques to enable its customers accelerated first silicon debug, reduced manufacturing ramp time, shortened failure analysis cycle time and improved yields. Teseda manufactures hardware and software solutions that capitalize on native scan structures within the circuit design to shorten the time to debug and accelerate time to market. Founded in 2001, Teseda is headquartered in Portland, Oregon. For more information, visit [www.teseda.com](http://www.teseda.com).

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